



SOT1533-2

LFBGA121, plastic, low profile fine-pitch ball grid array; 121 bumps; 0.65 mm pitch; 8 mm x 8 mm x 1.3 mm body

25 January 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA121
Package type industry code	LFBGA121
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	08-01-2016
Manufacturer package code	98ASA00423D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	8	-	mm
package width	-	8	-	mm
seated height	-	1.3	1.43	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	121	-	



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2 Package outline

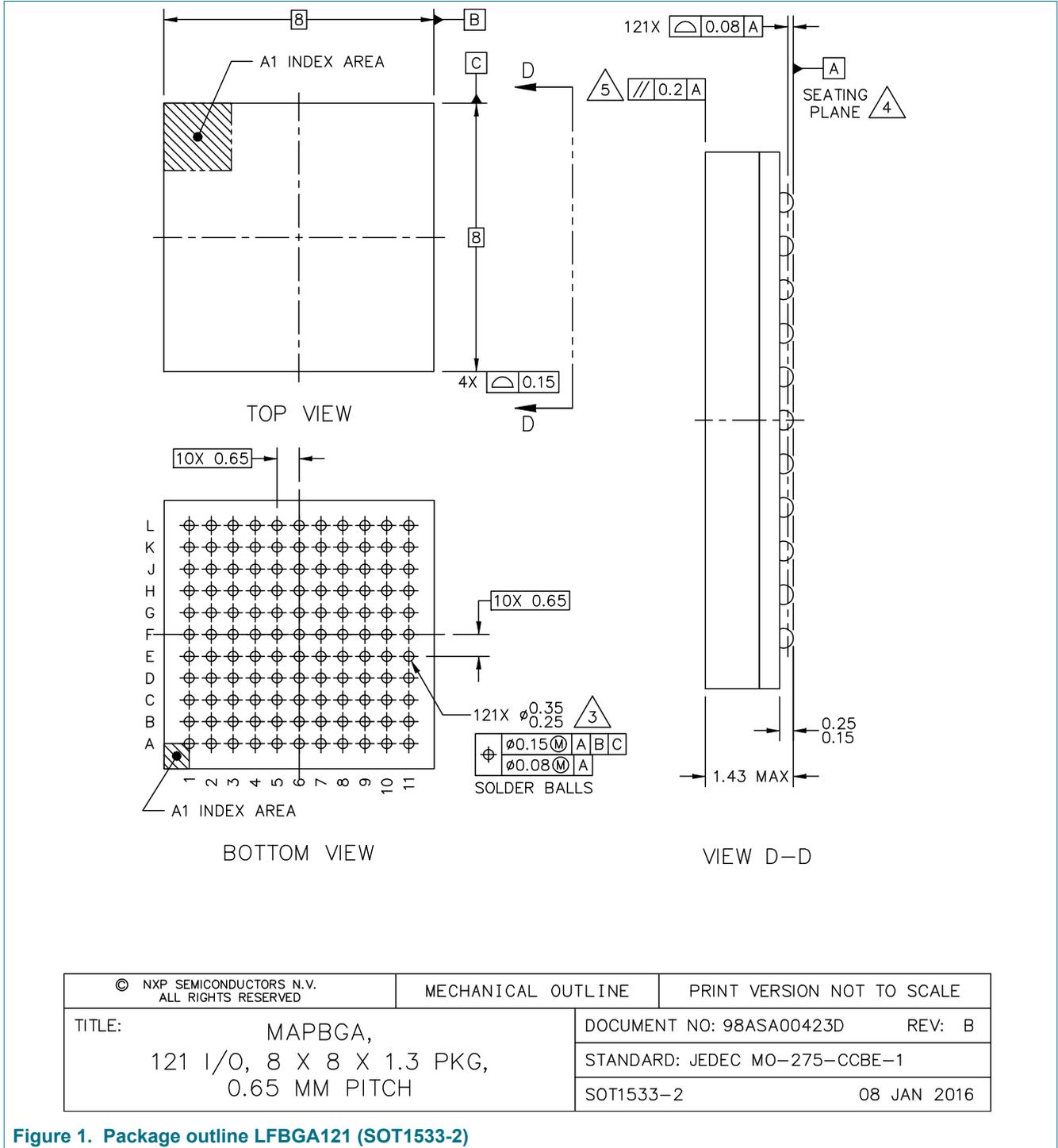


Figure 1. Package outline LFBGA121 (SOT1533-2)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: MAPBGA, 121 I/O, 8 X 8 X 1.3 PKG, 0.65 MM PITCH	DOCUMENT NO: 98ASA00423D	REV: B
	STANDARD: JEDEC MO-275-CCBE-1	
	SOT1533-2	08 JAN 2016

Figure 2. Package outline note LFBGA121 (SOT1533-2)

3 Legal information

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